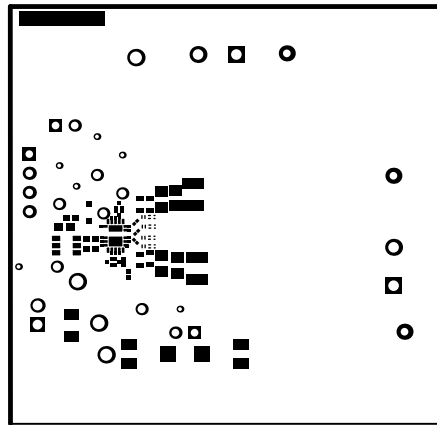
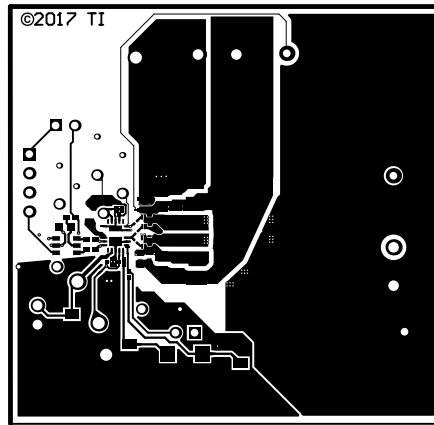


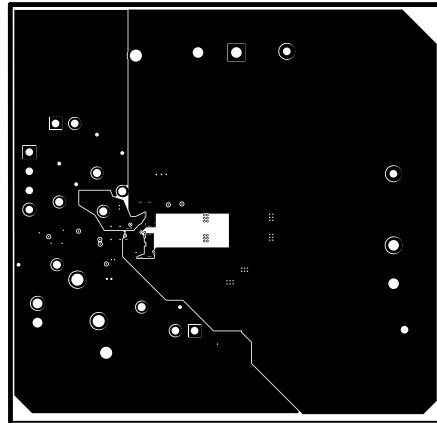
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01634	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 2/8/2018	3:24:27 PM	TEXAS INSTRUMENTS



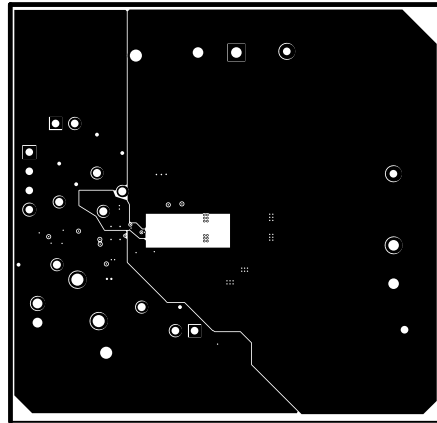
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01634	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 2/8/2018 3:24:31 PM	TEXAS INSTRUMENTS	



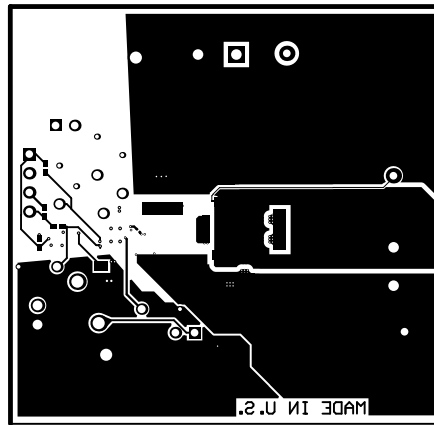
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01634	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 2/8/2018 3:24:34 PM	TEXAS INSTRUMENTS	



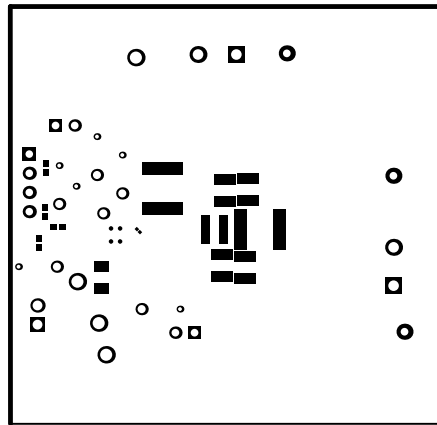
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01634	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = Signal Layer 1	GENERATED : 2/8/2018 3:24:37 PM	TEXAS INSTRUMENTS	



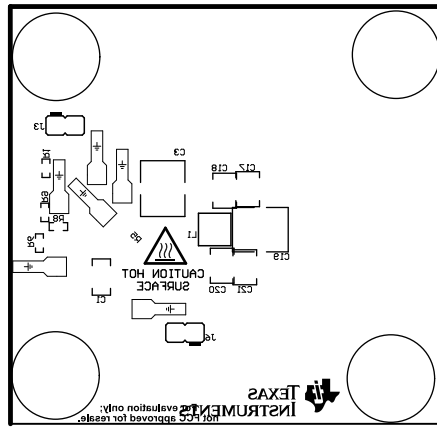
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01634	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = Signal Layer 2	GENERATED : 2/8/2018 3:24:41 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01634	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 2/8/2018 3:24:45 PM	TEXAS INSTRUMENTS	

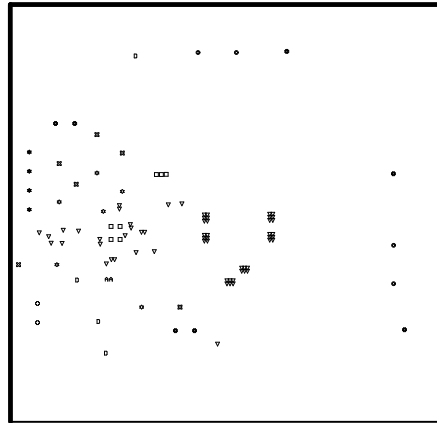


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01634	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 2/8/2018 3:24:47 PM	TEXAS INSTRUMENTS	



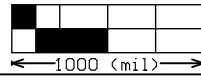
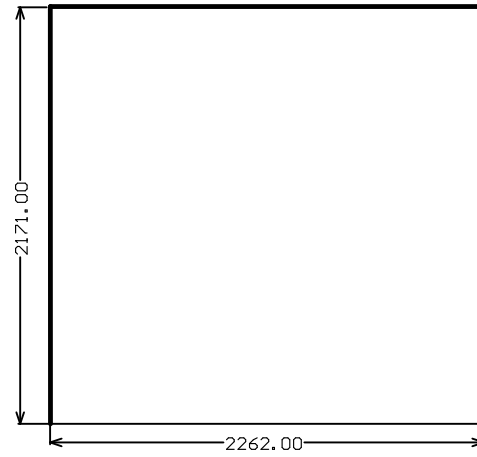
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01634	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 2/8/2018	3:24:49 PM	TEXAS INSTRUMENTS





Symbol	Count	Hole Size	Plated	Hole Type
Drill Pad	2	12.00mil (0.305mm)	PTH	Round
⊗	2	51.18mil (1.300mm)	PTH	Round
★	4	39.37mil (1.000mm)	PTH	Round
⊙	4	55.12mil (1.400mm)	PTH	Round
D	4	63.00mil (1.600mm)	PTH	Round
⊗	6	20.00mil (0.508mm)	PTH	Round
★	6	42.00mil (1.067mm)	PTH	Round
□	7	7.87mil (0.200mm)	PTH	Round
●	7	40.00mil (1.016mm)	PTH	Round
▽	59	7.00mil (0.178mm)	PTH	Round
<b>101 Total</b>				

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01634	REV: E1	SUN REV: Not In Version Control
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 2/8/2018	3:24:51 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01634	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 2/8/2018	3:24:54 PM	TEXAS INSTRUMENTS

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